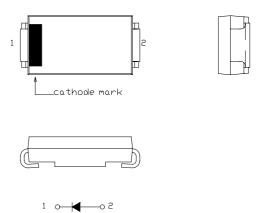
Nihon Inter Electronics Corporation

OUTLINE DRAWING

$\textbf{FRD} \quad \mathrm{Type}: NSF03A20$

FEATURES

- * FLAT-PAK Surface Mount Device
- * Ultra Fsat Recovery
- * High Surge Capability
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * Packaged in 16mm Tape and Reel
- * Not Rolling During Assembly



Maximum Ratings

Approx Net Weight:016g

Rating	Symbol	NSF03A20			Unit	
Repetitive Peak Reverse Voltage	V _{RRM}	200			V	
Average Rectified Output Current	Io	1.61	Ta=25 °C *1	50Hz Half Sine	A	
		3.0	T1=106 °C *2	Wave Resistive Load		
RMS Forward Current	I _F (RMS)	4.71			Α	
Surge Forward Current	I_{FSM}	45	50Hz Half Sine Wa	A		
			Non-repetitive			
Operating JunctionTemperature Range	T_{jw}	-40 to +150			$^{\circ}$ C	
Storage Temperature Range	T _{stg}	-40 to +150			°C	

Electrical • Thermal Characteristics

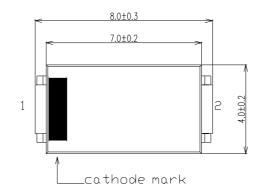
Characteristics	Symbol	Conditions		Тур.	Max.	Unit	
Peak Reverse Current	I_{RM}	Tj= 25°C, V _{RM} = V _{RRM}	-	-	10	μΑ	
Peak Forward Voltage	$V_{\rm FM}$	Tj= 25°C, I _{FM} = 3.0A	1	-	0.98	V	
Reverse Recovery Time	trr	Ta= 25°C, I_{FM} =3.0 A $-di/dt$ =50A/ μ s			30	ns	
Thermal Resistance	Rth _(j-a)	Junction to Ambient *1	ı	-	89	°C /W	
	Rth _(j-l)	Junction to Lead	-	-	13		

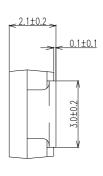
^{*1} Alumina Substrate Mounted (Soldering Lands=2x3.5mm,Both Sides)

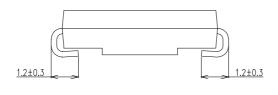
^{*2} Tl= Lead Temperature

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NSF03A20 OUTLINE DRAWING (Dimensions in mm)









SOLDERING PAD

